



1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material. non clad

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket

100 position BGA surface mount land pattern to terminal pins (0.8mm centers, 10x10 array)

**Tolerances:** diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA100C-61 Drawing</b>	Status: Released	Scale: 8:1	Rev: C
 <p>© 2005 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: S.Natarajan		Date: 5/3/05
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